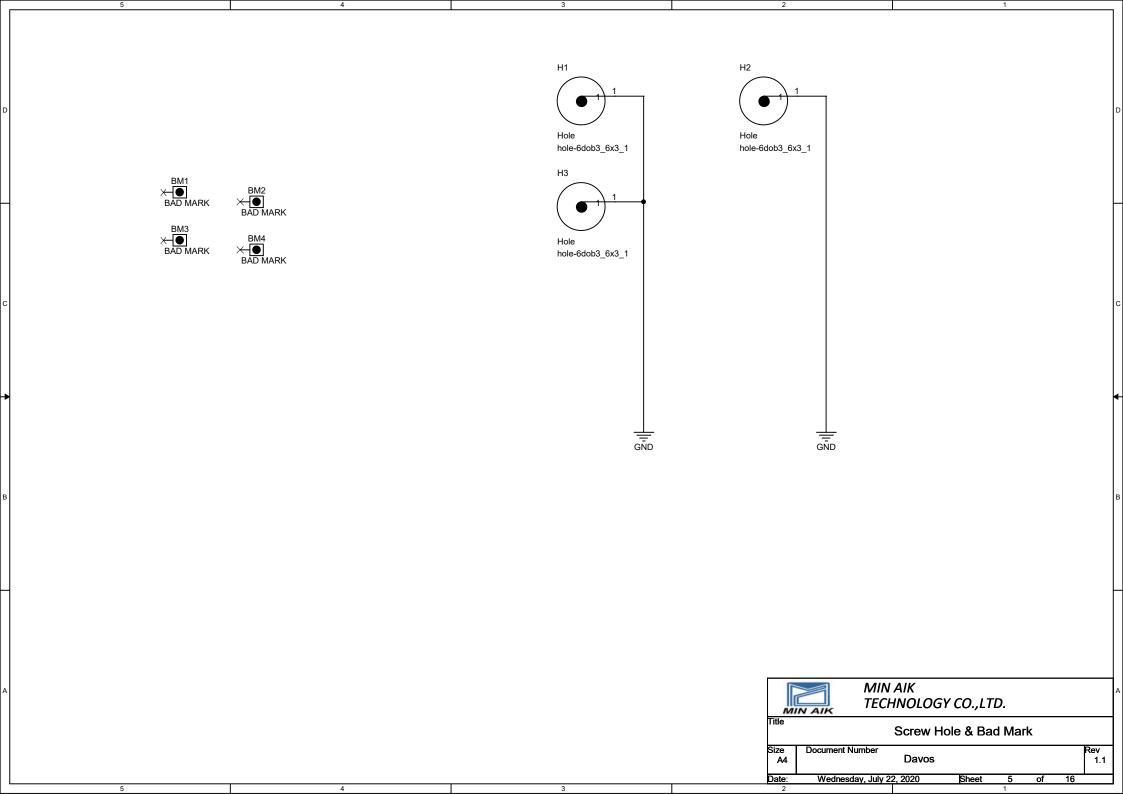
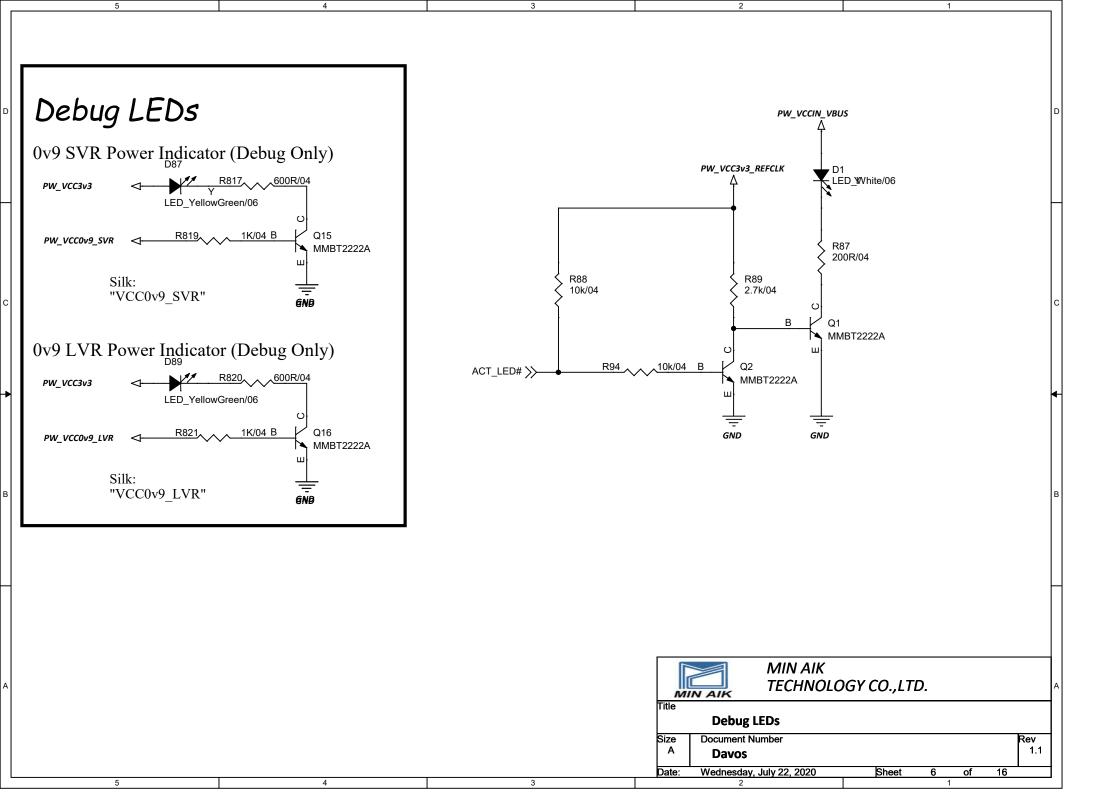
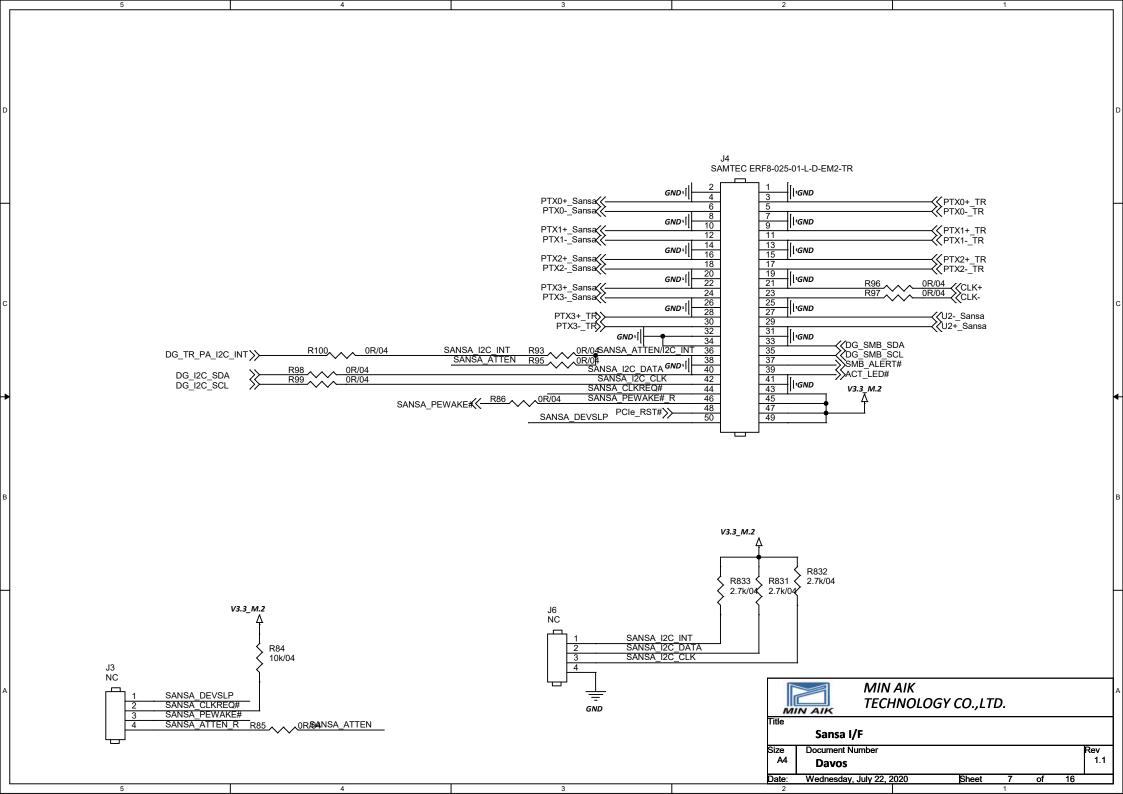


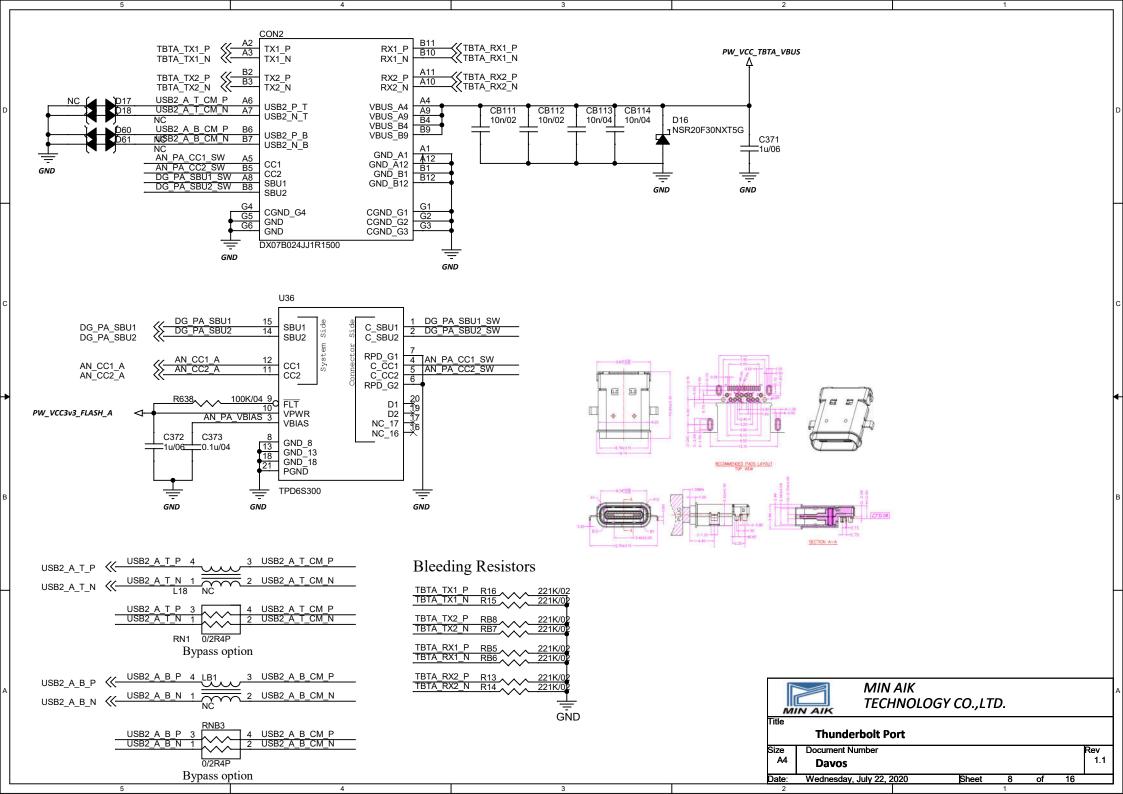
Stack-Up - FR4 FL-170 Control Impedance Via Type Differential 85Ω @ 5GHz Differential 100Ω @ 2GHz Core/PP Df Single 50Ω @ 1GHz TH Copper Layer Er (Dk) (PCIe, DP, MDI, HDMI & USB2) (CIO and USB3.1) Reference W1 D D Z Z Z Plane Layer Type Foil [Oz] Final [mil] [mil] @ 1GHz @ 2GHz @ 5GHz @ 1GHz @ 2GHz @ 5GHz Name Purpose v16c8 10GHz 10GHz [mil] [mil] [mil] [Ohm] [mil] [mil] [Ohm] [mil] [mil] [mil] [Ohm] Sig CS S 0.5 1.4 21 50.36 7.7 21 85.54 4.5 100.2 Ref (L2) 11 21 7628 CORE 7.00 4.30 4.10 3.90 4.00 0.014 0.015 0.015 0.015 L2 GND 1 1.2 GND 2116 PP 4.6 4.10 4.00 3.90 3.70 0.015 0.016 0.017 0.018 L3 Sig/PWR V 0.5 0.6 6.5 15 49.27 3.5 15 Ref (L2) 6x 2116 CORE 30 4.30 4.10 3.90 3.80 0.015 0.015 0.015 0.015 L4 Sig/PWR 6.5 15 49.27 0.5 0.6 3.5 15 99.89 Ref (L5) 2116 PP 4.00 3.70 0.017 0.018 4.6 4.10 3.90 0.015 0.016 L5 GND G 1 1.2 GND 7628 CORE 4.10 4.00 0.014 0.015 0.015 7.00 4.30 3.90 0.015 S 0.5 PS Sig 1.4 21 50.36 7.7 21 85.54 4.5 21 Ref (L5) 11 100.2 6.4 53.2 Total 4 mil Total 59.6 Total mm Remarks 1 W means Width of line 2 S means Spacing between the differential lines 3 D means Distance from other signals 4 Assuming W1 = W + 0.5mil for inner layers and W1 = W + 0.75mil for external layers 5 Assuming H1 = 0.5mil

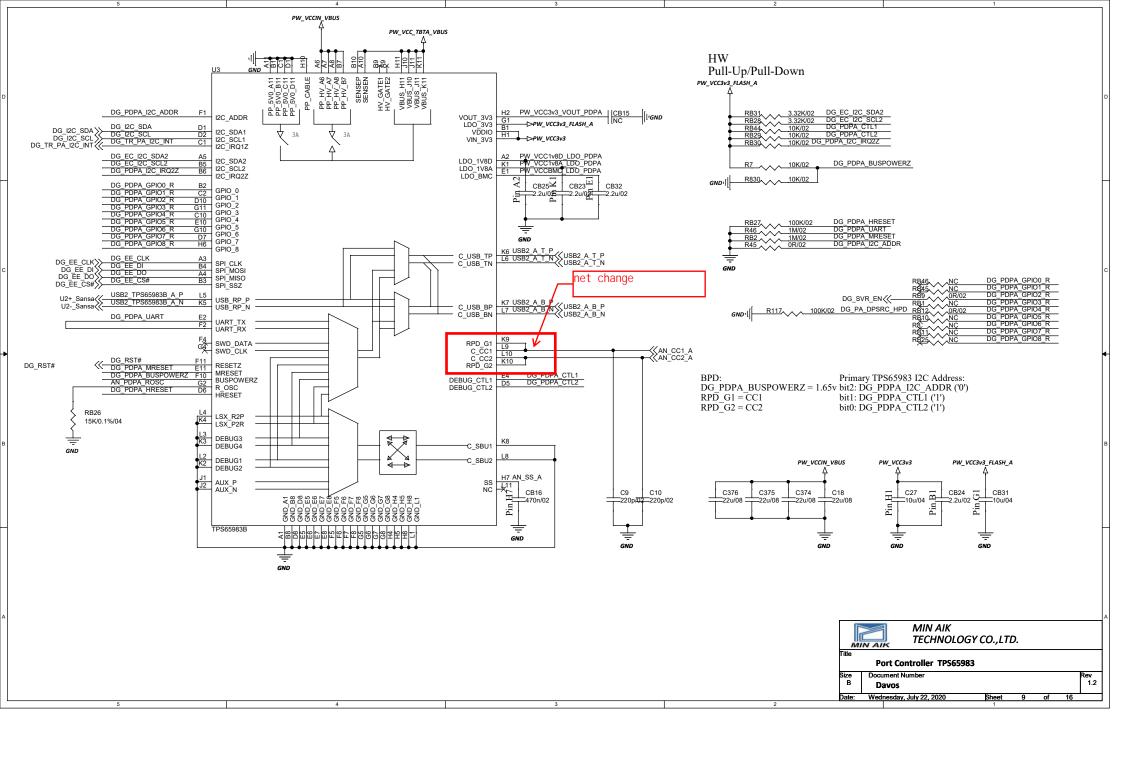
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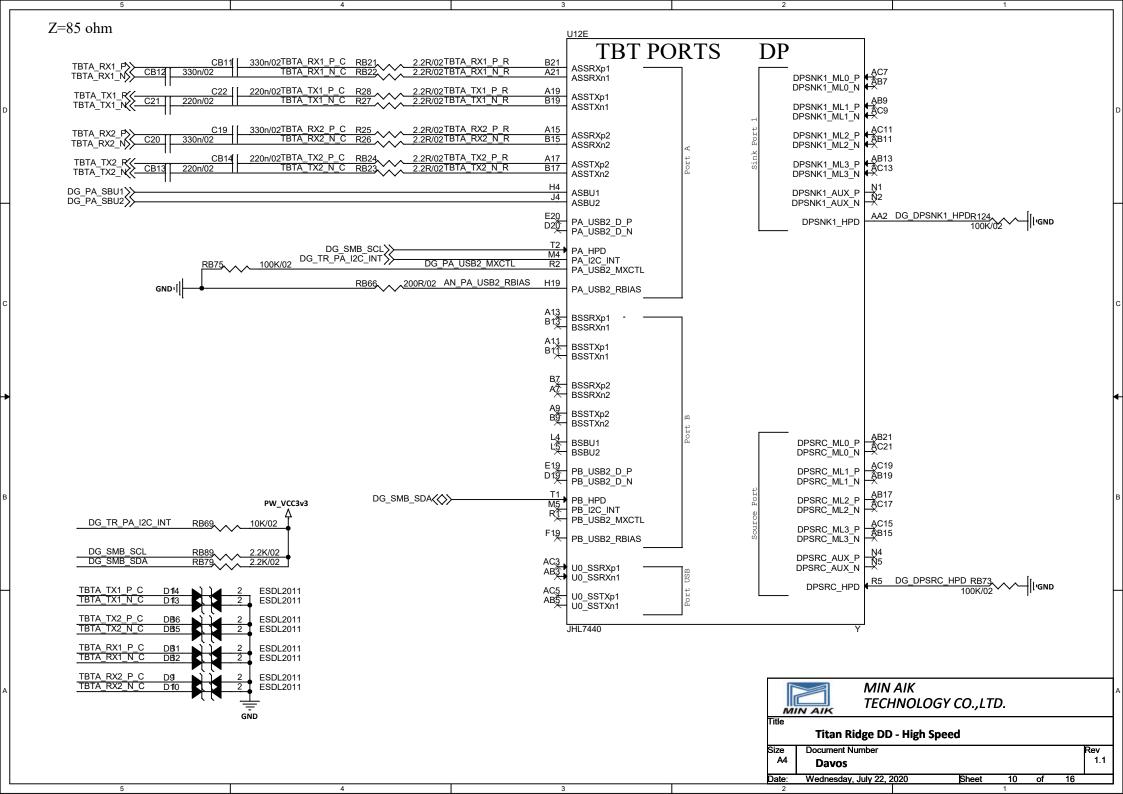


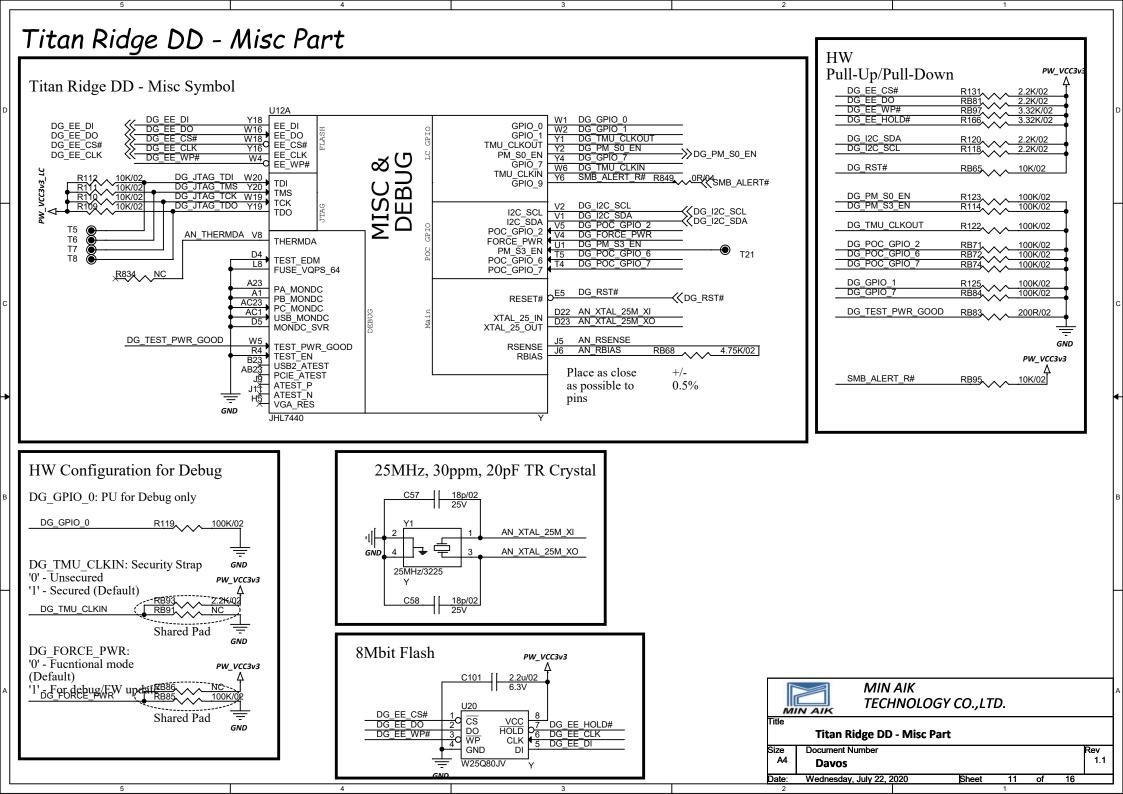












Titan Ridge DD - Power Supply & GND Parts

